

PMP7451_REVB BOM

COUNT	RefDes	Value	Description	Size	Part Number	MFR
1	C1	0.1uF	Capacitor, Ceramic, 50V, X7R, 15%	0603	STD	STD
1	C10	0.047uF	Capacitor, Ceramic, 250V, X7R, 15%	1206	STD	STD
2	C11, C18	0.1uF	Capacitor, Ceramic, 25V, X7R, 15%	0402	STD	STD
1	C15	330pF	Capacitor, Ceramic, 3kV, NP0, C0G, 10%	1808	Std	Std
1	C16	1uF	Capacitor, Ceramic, 6.3V, X5R, 15%	0402	STD	STD
1	C17	47pF	Capacitor, Ceramic, 50V, C0G, 5%	0402	STD	STD
1	C19	1000pF	Capacitor, Ceramic, 50V, C0G, 5%	0402	STD	STD
4	C2, C3, C4, C5	2.2uF	Capacitor, Ceramic, 100V, X7R, 15%	1210	STD	STD
1	C20	0.047uF	Capacitor, Ceramic, 25V, X7R, 15%	0402	STD	STD
1	C22	4700pF	Capacitor, Ceramic, 50V, C0G, 5%	0402	STD	STD
1	C23	4.7uF	Capacitor, Ceramic, 16V, X7R, 15%	1206	STD	STD
6	C6, C7, C8, C12, C13, C14	22uF	Capacitor, Ceramic, 16V, X5R, 15%	1206	STD	STD
1	C9	470uF	CAP ALUM 470UF 16V 20% RADIAL	0.315 inch	EEU-FR1C471	Panasonic
8	D1, D3, D4, D5, D6, D7, D10, D11	MMDL914T1	Diode, Switching, 100-V, 200-mA, 200-mW,	SOD-323	MMDL914T1	On Semi
1	D2	ES1D	DIODE ULTRAFAST 200V 1A DO-214AC	SMA	ES1D-13-F	Diodes Inc.
2	D8, D9	8.2V	Diode, Zener, 8.2V	SOD-323	BZT52B8V2S	STD
5	J1, J2, J5, J6, J7	8600-0-05-01-00-00-03-0	Header, Single pin	0.072 x 1 inch	8600-0-05-01-00-00-03-0	Mill-Max
2	J3, J4	8952-0-05-01-00-00-03-0	Header, Single pin	0.125 x 1 inch	8952-0-05-01-00-00-03-0	Mill-Max
1	L1	6.8uH	Inductor, Shielded Power, ±20%	0.394 x 0.445 inch	XAL1010-682ME	Coilcraft
1	L2	1mH	Inductor, SMT, 0.1A, ±20%	0.189 x 0.189 inch	LPS5015-105ML	Coilcraft
2	Q1, Q6	CSD18531Q5A	MOSFET N-CH 60V 100A	TDSO8-8	CSD18531Q5A	Texas Instruments
1	Q100	MMBT2907ALT1	Transistor, PNP, -60V, -600mA, 225-W		MMBT2907ALT1	
1	Q2	FDMS86200	MOSFET N-CH 150V POWER56	QFN	FDMS86200	Fairchild
1	Q3	SI1411DH	MOSFET P-CH 150V 420MA SC70-6	TSOP-6	SI1411DH	Vishay
2	Q4, Q5	BCX5616TA	TRANSISTOR NPN 80V SOT-89	SOT-89	BCX5616TA	Zetex
1	Q7	2N7002W	MOSFET, Nch, 60V, 115mA	SOT323 [SC70]	2N7002W	Diodes
1	R1	4.3	Resistor, Chip, 1/16W, 1%	0603	STD	STD
1	R12	66.5k	Resistor, Chip, 1/16W, 1%	0402	Std	Std
5	R13, R15, R21, R27, R29	100k	Resistor, Chip, 1/16W, 1%	0402	Std	Std
1	R14	52.3k	Resistor, Chip, 1/16W, 1%	0402	Std	Std
1	R16	2.21k	Resistor, Chip, 1/16W, 1%	0402	Std	Std
1	R17	0	Resistor, Chip, 1/16W, 1%	0402	Std	Std
1	R19	3.74k	Resistor, Chip, 1/16W, 1%	0402	Std	Std
4	R2, R8, R10, R24	1k	Resistor, Chip, 1/16W, 1%	0603	STD	STD
1	R20	1.65k	Resistor, Chip, 1/16W, 1%	0402	Std	Std
1	R22	2k	Resistor, Chip, 1/16W, 1%	0402	Std	Std
1	R23	100	Resistor, Chip, 1/16W, 1%	0603	STD	STD
1	R3	7.15k	Resistor, Chip, 1/2W, 5%	2010	STD	STD
1	R31	2.61k	Resistor, Chip, 1/16W, 1%	0402	Std	Std
2	R4, R6	2k	Resistor, Chip, 1/16W, 1%	0603	STD	STD
5	R5, R11, R25, R26, R28	10k	Resistor, Chip, 1/16W, 1%	0402	Std	Std
2	R7, R18	1k	Resistor, Chip, 1/16W, 1%	0402	Std	Std
1	R9	15k	Resistor, Chip, 1/16W, 1%	0402	Std	Std
1	T1	CST2-100L	Transformer, Current Sense, 100:1	0.315 x 0.320 inch	CST2-100L	Coilcraft
1	T2	150 uH	Xfmr, 140W		PA0801.004	
2	U1, U4	TCMT1107	IC, Photocoupler	MF4	TCMT1107	Vishay
1	U2	UCC2897ARTJ	IC, Advanced Current-Mode Active Clamp PWM Controller	QFP-20	UCC2897ARTJ	TI
2	U3, U5	TL431AIDBZR	IC, Precision Adjustable Shunt Regulator	SOT23-3	TL431AIDBZR	TI

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